

4,4'-diaminodiphenylether; a combination of 1,2-(ethylene)bis(trimellitate anhydride) and bis(4-amino-3,5-diisopropylphenyl)methane; a combination of 1,2-(ethylene)bis(trimellitate anhydride) and 2,2-bis[4-(4-aminophenoxy)phenyl] propane; a combination of a mixture of 1,2-(ethylene)bis(trimellitate anhydride) and 1,10-(decamethylene)bis(trimellitate anhydride) being the same mol as the mixture and 2,2-bis[4-(4-aminophenoxy)phenyl] propane; and a combination of 1,10-(decamethylene)bis(trimellitate anhydride) and 2,2-bis[4-(4-aminophenoxy)phenyl] propane.

46. The semiconductor device according to claim 25, 26, 27, 28, 29, 30 or 31, wherein the die-bonding material contains a metal filler.

47. A semiconductor device according to claim 25, 26, 27, 28, 29, 30 or 31, wherein said die-bonding material is a film comprising polyimide resin and epoxy resin. --

REMARKS

With the above amendments, the specification has been amended to identify and incorporate by reference the parent application, i.e., Serial No. 08/981,702, as well as the international application and Japanese application upon which the present application claims priority.

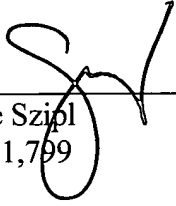
Additionally, all of the claims originally filed with the parent application, i.e., claims 1-24, have been cancelled and new claims 25-47 have been inserted for prosecution in this continuation application.

Accordingly, it is believed that this application is in good condition for examination, and the Examiner's early and favorable action is respectfully solicited.

Questions are welcomed by the below-signed attorney for applicants.

Respectfully submitted,

GRIFFIN & SZIPL, PC



Joerg-Uwe Szipl
Reg. No. 31,799

GRIFFIN & SZIPL, PC
Suite PH-1
2300 Ninth Street, South
Arlington, VA 22204

Telephone: (703) 979-5700
Facsimile: (703) 979-7429
Customer No.: 24203

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